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IECON'01

Sponsored by: IEEE Industrial Electronics Society
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Special Session on Survivable Systems and Networks

organized and co-chaired by
Axel Krings, University of Idaho, krings@cs.uidaho.edu
Azad Azadmanesh, University of Nebraska at Omaha, azad@ahvaz.unomaha.edu
and Miles McQueen, INEEL, amm@inel.gov

Call For Papers

Topics of interest include, but are not limited to:

- Survivability architectures.
- Design and analysis of survivable systems.
- Information assurance of mission critical systems.
- Infrastructure protection.
- Dependability in the presence of malicious faults.
- Attack tolerance.
- Hardware/Software hybrid solutions.
- Survivability issues in task scheduling.
- Redundancy management, system recovery.
- Distributed agreement.
- General issues in system survivability.
- Other topics related to the conference scope and/or of interest to the prospective conference participants.

Submission of Papers: The working language of the conference is English. Submit a full paper using the following layout: Page 1: title, authors' names, mailing address, phone, fax, and email of each author. Identify the contact author, preferred topical area, subject area and keywords. Page 2: title, authors' affiliations, 100-200 words abstract. Pages 3-8: full paper limited to 6 pages, including figures and references. Submit full papers in postscript or pdf format by e-mail to krings@cs.uidaho.edu.

Author's Schedule:

Extended Deadline for Submission of Full Papers: April 15, 2001
Notification of Acceptance: June 10, 2001
Deadline for Submission of Final Manuscripts: August 15, 2001

For general information please check the conference web page:

<http://sant.bradley.edu/~iecon01/>

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karel.jezernik@uni-mb.si

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MIT, USA
masaki@mit.edu

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